INTEGRATED CIRCUITS

DATA SHEET

CBT3245A Octal bus switch

Product data Supersedes data of 2002 Feb 18





Octal bus switch CBT3245A

FEATURES

- Standard '245-type pinout
- ullet 5 Ω switch connection between two ports
- TTL compatible control input levels
- Package options include plastic small outline (D), shrink small outline (DB), thin shrink small outline (TSSOP)
- Latch-up protection exceeds 500 mA per JESD78
- ESD protection exceeds 2000 V HBM per JESD22-A114,
 150 V MM per JESD22-A115 and 1000 V CDM per JESD22-C101

DESCRIPTION

The CBT3245A provides eight bits of high-speed TTL-compatible bus switching in a standard '245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The CBT3245A device is organized as one 8-bit switch. When enable (\overline{OE}) is LOW, the switch is on and port A is connected to port B. When \overline{OE} is HIGH, the switch is open and a high-impedance state exists between the two ports.

The CBT3245A is characterized for operation from -40 to +85 °C.

$\begin{array}{ll} {\sf PIN~CONFIGURATION-SO,~SSOP,~QSOP,~AND}\\ {\sf TSSOP} \end{array} \\$

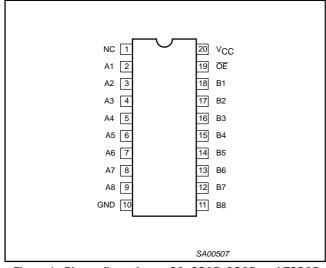


Figure 1. Pin configuration — SO, SSOP, QSOP, and TSSOP

PIN CONFIGURATION — DHVQFN

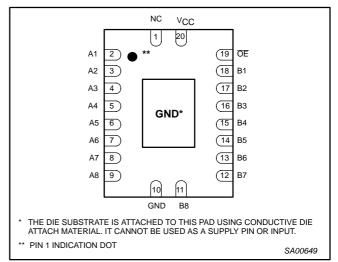


Figure 2. Pin configuration — DHVQFN (top view)

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION				
1	NC	No internal connection				
19	ŌĒ	Output enable input				
2, 3, 4, 5, 6, 7, 8, 9	A1-A8	Inputs				
18, 17, 16, 15, 14, 13, 12, 11	B1-B8	Outputs				
10	GND	Ground (0V)				
20	V _{CC}	Positive supply voltage				

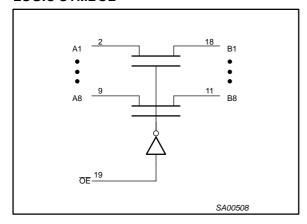
ORDERING INFORMATION

ONDERNING INI ORMAI	1011			
PACKAGES	TEMPERATURE RANGE	ORDER CODE	TOPSIDE MARK	DWG NUMBER
20-Pin Plastic DHVQFN	-40 to 85 °C	CBT3245ABQ	CT3245A	SOT764-1
20-Pin Plastic TSSOP	-40 to 85 °C	CBT3245APW	CT3245A	SOT360-1
20-Pin Plastic SSOP (QSOP)	-40 to 85 °C	CBT3245ADS	CT3245ADS	SOT724-1
20-Pin Plastic SSOP	-40 to 85 °C	CBT3245ADB	CT3245A	SOT339-1
20-Pin Plastic SO	-40 to 85 °C	CBT3245AD	CBT3245AD	SOT163-1

Standard packing quantities and other packaging data is available at www.philipslogic.com/packaging.

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LOGIC SYMBOL



FUNCTION TABLE

INPUT	INPUTS/OUTPUTS
ŌĒ	A, B
L	A = B
Н	Z

H = HIGH voltage level L = LOW voltage level

Z = HIGH impedance "off" state

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
VI	DC input voltage ³		-0.5 to +7.0	V
lok	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	output in Off or HIGH state	-0.5 to +7	V
I _{OUT}	DC output current	output in LOW state	128	mA
T _{stg}	Storage temperature range		-65 to 150	°C

NOTES

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
STIVIBUL	PARAMETER	MIN	MAX	UNII
V _{CC}	DC supply voltage	4.0	5.5	V
V _{IH}	HIGH-level input voltage	2.0	_	V
V _{IL}	LOW-level input voltage	_	0.8	V
T _{amb}	Operating free-air temperature range	-40	+85	°C

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

^{3.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

				LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	T _{amb}	UNIT			
			MIN	TYP ¹	MAX	7	
V _{IK}	Input clamp voltage	V _{CC} = 4.5 V; I _I = -18 mA	_	_	-1.2	V	
I _I	Input leakage current	V _{CC} = 5.5 V; V _I = GND or 5.5 V	_	_	±5	μΑ	
Icc	Quiescent supply current	$V_{CC} = 5.5 \text{ V}; I_{O} = 0, V_{I} = V_{CC} \text{ or GND}$	_	1	3	μΑ	
Δl _{CC}	Additional supply current per input pin ²	V_{CC} = 5.5 V, one input at 3.4 V, other inputs at V_{CC} or GND	_	_	3.5	mA	
CI	Control pins	V _I = 3 V or 0, \overline{OE} = V _{CC}	_	3.2	_	pF	
C _{IO(OFF)}	Pin capacitance (OFF state)	V _O = 3 V or 0	_	6.6	_	pF	
		V _{CC} = 4.5 V; V ₁ = 0 V; I _I = 64 mA	_	5	7		
r_{on}^3	On-resistance	$V_{CC} = 4.5 \text{ V}; V_1 = 0 \text{ V}; I_1 = 30 \text{ mA}$	_	5	7	Ω	
		$V_{CC} = 4.5 \text{ V}; V_1 = 2.4 \text{ V}; I_1 = 15 \text{ mA}$	_	10	15	1	

NOTES:

- All typical values are at V_{CC} = 5 V, T_{amb} = 25 °C
 This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND
 Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

AC CHARACTERISTICS

 $GND = 0 V; t_{R;} C_{L} = 50 pF$

				СВТЗ		
SYMBOL	PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _{amb} = -40 V _{CC} = +5.0	UNIT	
				MIN	MAX	
t _{pd}	Propagation delay ¹	A or B	B or A		0.25	ns
t _{en}	Output enable time to HIGH and LOW level	ŌĒ	A or B	1.0	5.9	ns
t _{dis}	Output disable time from HIGH and LOW level	ŌĒ	A or B	1.0	6.0	ns

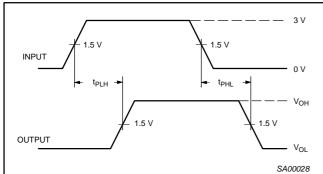
NOTES:

^{1.} This parameter is warranted but not production tested. The propagation delay is based on the RC time constant of the typical on-state resistance of the switch and a load capacitance of 50 pF, when driven by an ideal voltage source (zero output impedance).

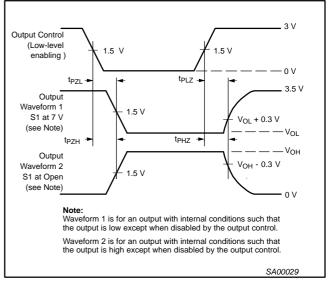
Octal bus switch CBT3245A

AC WAVEFORMS

 $V_M = 1.5 \text{ V}, V_{IN} = \text{GND to } 3.0 \text{ V}$

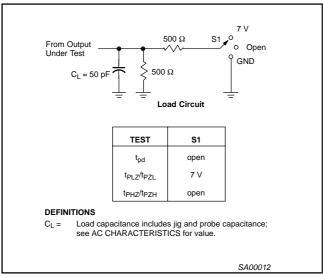


Waveform 1. Input to Output Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORMS



NOTES:

1. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega,~t_f \leq 2.5~ns,~t_f \leq 2.5~ns$.

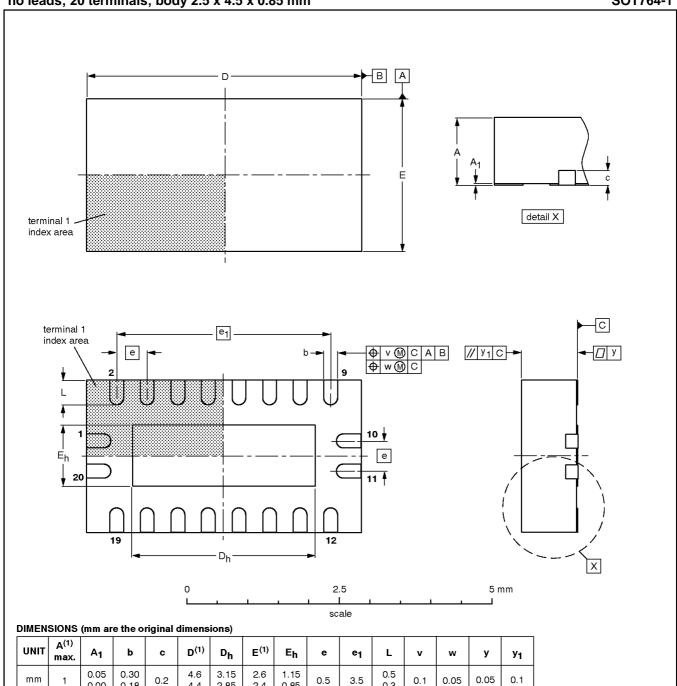
5

2. The outputs are measured one at a time with one transition per measurement.

Octal bus switch CBT3245A

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1



Note

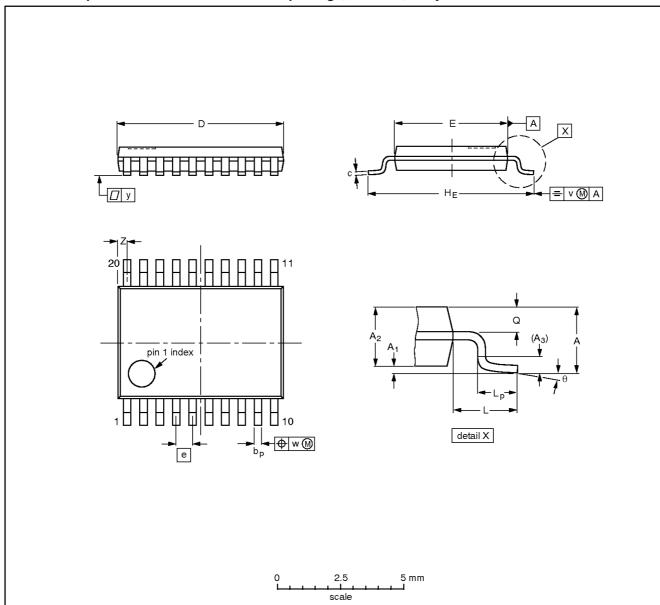
1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	1330E DATE
SOT764-1		MO-241				-02-10-17 03-01-27

Octal bus switch CBT3245A

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	O	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	a	v	w	у	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

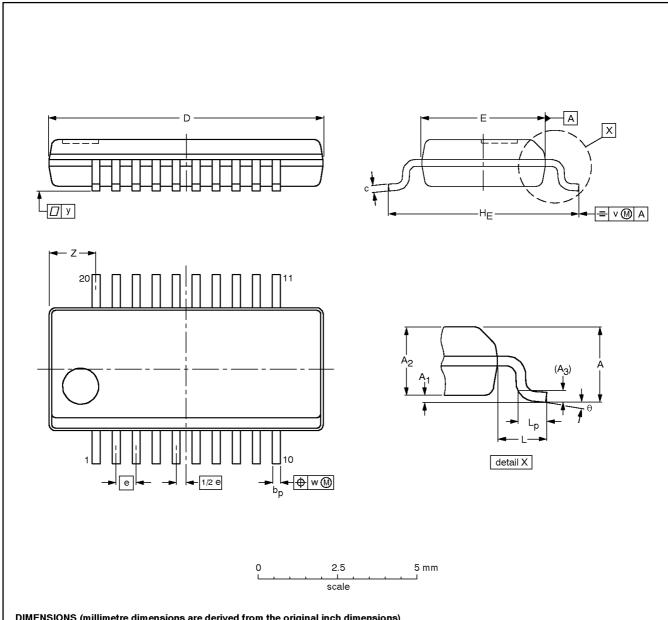
- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT360-1		MO-153			€	-99-12-27 03-02-19	

Octal bus switch **CBT3245A**

SSOP20: plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm

SOT724-1



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽¹⁾	e	HE	L	Lp	>	¥	у	Z ⁽¹⁾	θ
mm	1.73	0.25 0.10	1.55 1.40	0.25	0.31 0.20	0.25 0.18	8.8 8.6	4.0 3.8	0.635	6.2 5.8	1	0.89 0.41	0.25	0.18	0.1	1.67 1.28	8° 0°

Note

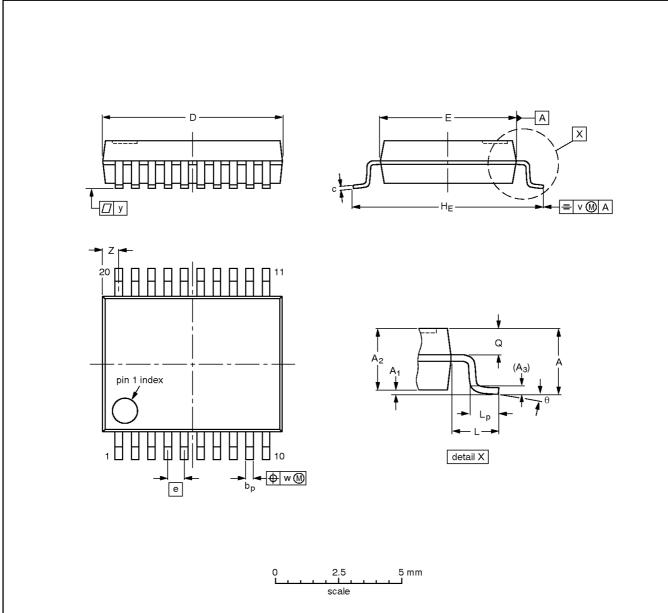
1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT724-1		MO-137				-01 07 04 03-02-18

Octal bus switch CBT3245A

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

Note

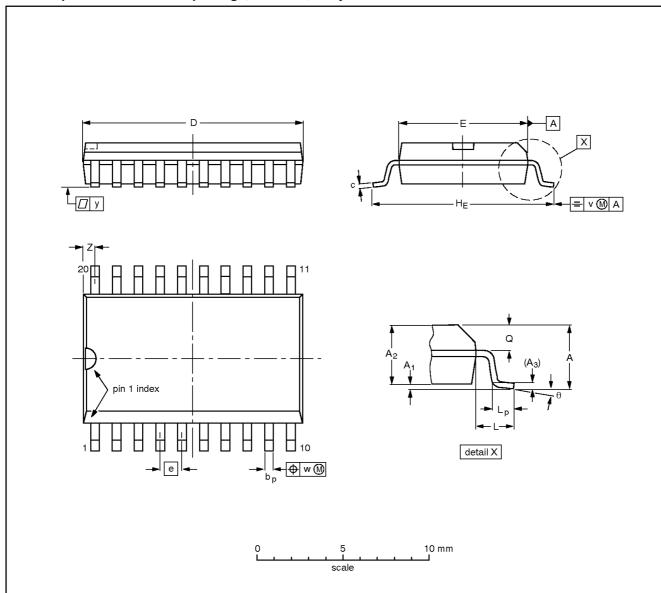
1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT339-1		MO-150				-99-12-27- 03-02-19

Octal bus switch CBT3245A

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055		0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013				-99-12-27 03-02-19	

Octal bus switch CBT3245A

REVISION HISTORY

Rev	Date	Description
_2	20030627	Product data (9397 750 11679); ECN 853-2313 30017 dated 11 Jun 2003. Supersedes data of 2002 Feb 18 (9397 750 09462).
		Modifications:
		 Addition of QSOP and DHVQFN package types.
_1	20020218	Product data (9397 750 09462); ECN 853-2313 27745 of 18 Feb 2002.

Octal bus switch CBT3245A

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions						
1	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.						
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III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).						

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- [2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
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Definitions

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